



Material Content Data Sheet



Sales Product Name				IPG16N10S4-61		Issued		4. July 2019	
MA#				MA001616830					
Package				PG-TDSON-8-4		Weight*		96.04 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip_1	inorganic material	silicon	7440-21-3	0.692	0.72	0.72	7205	7205	
chip_2	inorganic material	silicon	7440-21-3	0.692	0.72	0.72	7205	7205	
leadframe	inorganic material	phosphorus	7723-14-0	0.013	0.01		139		
	non noble metal	iron	7439-89-6	0.044	0.05		463		
wire	non noble metal	copper	7440-50-8	44.409	46.24	46.30	462415	463017	
	non noble metal	aluminium	7429-90-5	0.717	0.75	0.75	7467	7467	
encapsulation	organic material	carbon black	1333-86-4	0.092	0.10		956		
	plastics	epoxy resin	-	6.520	6.79		67888		
	inorganic material	silicondioxide	60676-86-0	39.303	40.92	47.81	409243	478087	
leadfinish	non noble metal	tin	7440-31-5	1.308	1.36	1.36	13616	13616	
plating	inorganic material	phosphorus	7723-14-0	0.000	0.00		1		
	non noble metal	nickel	7440-02-0	0.048	0.05	0.05	500	501	
solder	non noble metal	tin	7440-31-5	0.039	0.04		407		
	noble metal	silver	7440-22-4	0.049	0.05		509		
	non noble metal	lead	7439-92-1	1.866	1.94	2.03	19432	20348	
heatspreader	inorganic material	phosphorus	7723-14-0	0.000	0.00		1		
	non noble metal	iron	7439-89-6	0.000	0.00		3		
	non noble metal	copper	7440-50-8	0.245	0.26	0.26	2550	2554	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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